SN54F541, SN74F541 OCTAL BUFFERS/DRIVERS WITH 3-STATE OUTPUTS SDFS021A – D3126, JANUARY 1989 – REVISED OCTOBER 1993

- 3-State Outputs Drive Bus Lines or Buffer Memory Address Registers
- Data Flow-Through Pinout (All Inputs on Opposite Side From Outputs)
- Package Options Include Plastic Small-Outline Packages, Ceramic Chip Carriers, and Plastic and Ceramic DIPs

description

The 'F541 octal buffer/line driver is ideal for driving bus lines or buffering memory address registers. The device features inputs and outputs on opposite sides of the package to facilitate printed-circuit-board layout.

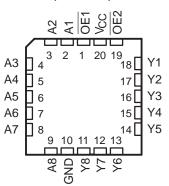
The 3-state control gate is a 2-input AND gate with active-low inputs so that if either output enable $(\overline{OE1} \text{ or } \overline{OE2})$ input is high, all eight outputs are in the high-impedance state.

The SN54F541 is characterized for operation over the full military temperature range of -55° C to 125°C. The SN74F251 is characterized for operation from 0°C to 70°C.

SN54F541 J I	PACKAGE
SN74F541 DW OI	R N PACKAGE
(TOP VIE	W)

OE1	1	U	20] v _{cc}
A1 [2		19] OE2
A2 [3		18] Y1
A3 [4		17] Y2
A4 [5		16] Y3
A5 [6		15] Y4
A6 [7		14] Y5
A7 [8		13] Y6
A8 [9		12	Y 7
gnd [10		11] Y8

SN54F541 ... FK PACKAGE (TOP VIEW)



FUNCTION TABLE

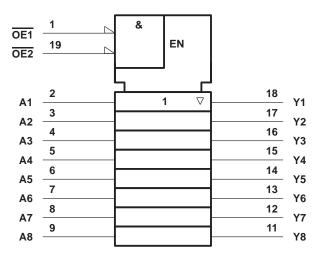
	INPUTS		OUTPUT
OE1	OE2	Α	Y
L	L	L	L
L	L	Н	н
н	Х	Х	Z
Х	Н	Х	Z

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

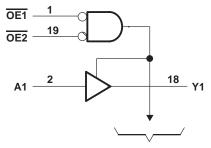
SN54F541, SN74F541 OCTAL BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

SDFS021A - D3126, JANUARY 1989 - REVISED OCTOBER 1993

logic symbol[†]



logic diagram (positive logic)



To Seven Other Channels

[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[‡]

Supply voltage range, V _{CC} Input voltage range, V _I (see Note 1) Input current range	\ldots -1.2 V to 7 V
Voltage range applied to any output in the disabled or power-off state	
Voltage range applied to any output in the high state	\dots –0.5 V to V _{CC}
Current into any output in the low state: SN54F541	96 mÅ
SN74F541	
Operating free-air temperature range: SN54F541	−55°C to 125°C
SN74F541	0°C to 70°C
Storage temperature range	–65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
NOTE 1: The input voltage ratings may be exceeded provided the input current ratings are observed.

recommended operating conditions

		s	N54F54	1	S	UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.8			0.8	V
Iк	Input clamp current			-18			-18	mA
IOH	High-level output current			- 12			- 15	mA
I _{OL}	Low-level output current			48			64	mA
TA	Operating free-air temperature	-55		125	0		70	°C



SN54F541, SN74F541 **OCTAL BUFFERS/DRIVERS** WITH 3-STATE OUTPUTS

SDFS021A - D3126, JANUARY 1989 - REVISED OCTOBER 1993

		TEST CONDITIONS				S	N74F54	1	LINUT
PARAMETER	IE	ST CONDITIONS	MIN	түр†	MAX	MIN	TYP†	MAX	UNIT
VIK	V _{CC} = 4.5 V,	lj = - 18 mA			-1.2			-1.2	V
		I _{OH} = – 3 mA	2.4	3.3		2.4	3.3		
Vari	$V_{CC} = 4.5 V$	I _{OH} = - 12 mA	2	3.2					v
VOH		I _{OH} = - 15 mA				2	3.1		v
	V _{CC} = 4.75 V,	I _{OH} = – 3 mA				2.7			
Max		I _{OL} = 48 mA		0.38	0.55				v
VOL	$V_{CC} = 4.5 V$	I _{OL} = 64 mA					0.42	0.55	V
IOZH	V _{CC} = 5.5 V,	V _O = 2.7 V			50			50	μΑ
I _{OZL}	V _{CC} = 5.5 V,	V _O = 0.5 V			-50			-50	μΑ
lj	V _{CC} = 5.5 V,	VI = 7 V			0.1			0.1	mA
Чн	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μA
۱ _{IL}	V _{CC} = 5.5 V,	VI = 0.5 V			- 0.6			- 0.6	mA
IOS‡	V _{CC} = 5.5 V,	V _O = 0	-100		-225	-100		-225	mA
		Outputs high		28	35		28	35	
ICC	V _{CC} = 5.5 V	Outputs low		62	75		62	75	mA
		Outputs disabled		40	55		40	55	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[‡]Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

switching characteristics (see Note 2)

PARAMETER	FROM (INPUT)	ТО (OUTPUT)	CI RI	CC = 5 V _ = 50 pl _ = 500 s _ = 25°C	F, Ω,	CL RL	= 50 pF = 500 Ω			UNIT
				′ F541		SN54	F541	SN74		
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
^t PLH	Any A	Y	1.5	3.3	5.5	1	6.5	1.5	6	ns
^t PHL	Ally A	ř	1.5	2.7	5.5	1	6.5	1.5	6	115
^t PZH	OE	Y	3	5.8	8	1.7	10	2.5	9.5	ns
^t PZL	ÛE	ř	3.5	6.1	8.5	2.2	10	3	9.5	115
^t PHZ	ŌĒ	v	1.5	3.4	6	1	7	1.5	6.5	ns
^t PLZ	UL UL		1.5	2.9	5.5	1	7.5	1.5	6	115

§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. NOTE 2: Load circuits and waveforms are shown in Section 1.





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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9175301M2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9175301M2A SNJ54F541FK	Samples
5962-9175301MRA	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9175301MR A SNJ54F541J	Samples
SN74F541DW	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	F541	Samples
SN74F541DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	F541	Samples
SN74F541N	ACTIVE	PDIP	Ν	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74F541N	Samples
SN74F541NSR	ACTIVE	SO	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74F541	Samples
SNJ54F541FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9175301M2A SNJ54F541FK	Samples
SNJ54F541J	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9175301MR A SNJ54F541J	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

ROHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



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⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54F541, SN74F541 :

- Catalog: SN74F541
- Military: SN54F541

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74F541DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74F541NSR	SO	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

6-May-2017



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74F541DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74F541NSR	SO	NS	20	2000	367.0	367.0	45.0

LEADLESS CERAMIC CHIP CARRIER

FK (S-CQCC-N**) 28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



DW0020A



PACKAGE OUTLINE

SOIC - 2.65 mm max height

SOIC



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M. 2. This drawing is subject to change without notice. 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



DW0020A

EXAMPLE BOARD LAYOUT

SOIC - 2.65 mm max height

SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



DW0020A

EXAMPLE STENCIL DESIGN

SOIC - 2.65 mm max height

SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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